



NOTES:

- MATERIALS:
HOUSING: LCP, UL94V-0;
TERMINAL: COPPER ALLOY;
- FINISHES:
TERMINAL:
1.27μM MIN. NICKEL UNDERPLATING OVERALL,
0.38μM MIN. GOLD PLATING ON CONTACT AREA;
0.05μM MIN. GOLD FLASH PLATING ON SOLDERING TAIL AREA;
- PRODUCT SPECIFICATION: PS-151130-0001;
- PACKAGING SPECIFICATION: PK-151130-0001;
- NO CIRCUIT ALLOWED UNDER CONNECTOR;
- DATE CODE PRINTED: XXX,
DAY OF THE YEAR

THIS DESIGN IS BASED ON DESIGN OBJECTIVES AND IS STRICTLY TENTATIVE. IT MAY CHANGE BASED ON RESULTS OF ADDITIONAL DESIGN REVIEWS & VERIFICATIONS.

DRAWING REVISE EC NO: S2015-1463 DRW:HLWANG06 2015/06/16 CHKD:JZENG 2015/06/16 APPR:HLWANG06 2015/06/16	QUALITY SYMBOLS FA=0 FC=0 FB=0	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE NTS	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION		
			mm	INCH	DRAWN BY HLWANG06	DATE 2014/11/25	TITLE SALES DRAWING FOR 0.38MM HEIGHT BLOCK SIM CONNECTOR			
		4 PLACES	± ---	± ---	CHECKED BY JZENG	DATE 2014/12/22	DOCUMENT NO. SD-151130-0001			
		3 PLACES	± ---	± ---	APPROVED BY HLWANG06	DATE 2014/12/23				
4	REV	DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		SIZE A3	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION					